

General Description

The WSD2050DN is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD2050DN meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

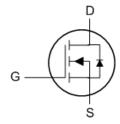
BVDSS	RDSON	ID
20V	8.2 m Ω	40A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN3.3x3.3-8_EP1 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	±12	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	40	Α
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	28	Α
I _{DM}	Pulsed Drain Current ²	85	А
I _{AS} Avalanche Current		14	Α
P _D @T _C =25℃ Total Power Dissipation ⁴		28	W
T _J T _{STG}	-55 to 150	$^{\circ}$	

Thermal Data

Symbol	Parameter		Max.	Unit
R _{0JA}	Thermal Resistance Junction-Ambient ¹		70	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		50	°C/W
R ₀ JC	Thermal Resistance Junction-Case ¹		4.7	°C/W



Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage V _{GS} =0V , I _D =250uA		20			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I _D =1mA		0.0		V/℃	
	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =7A		8.2	14	mΩ	
-		V _{GS} =4.5V , I _D =6A		9.5	16		
R _{DS(ON)}	Static Drain-Source On-Nesistance	V _{GS} =2.5V , I _D =5A		12.5	20	mΩ	
		V _{GS} =1.8V , I _D =2A		18	28		
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	0.4	0.6	1.0	V	
	Drain Source Leakage Current	V _{DS} =20V , V _{GS} =0V , T _J =25℃			1	uA	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =20V , V _{GS} =0V , T _J =55℃			5		
I _{GSS}	Gate-Source Leakage Current	e Leakage Current $V_{GS}=\pm12V$, $V_{DS}=0V$			±100	nA	
gfs	orward Transconductance V _{DS} =5V , I _D =7A		20			S	
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.0	1.5	Ω	
Q_g	Total Gate Charge (4.5V)			10	12		
Q_gs	Gate-Source Charge	V _{DS} =15V , V _{GS} =10V , I _D =7A		3.5	4.1	nC	
Q _{gd}	Gate-Drain Charge			4.2	4.7		
T _{d(on)}	Turn-On Delay Time			9	17		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =6 Ω		11	23		
T _{d(off)}	Turn-Off Delay Time	$I_D=1A$,RL=15 Ω		29	52	ns	
T _f	Fall Time			7	12		
C _{iss}	Input Capacitance			1200			
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		185		pF	
C _{rss}	Reverse Transfer Capacitance			113			

Diode Characteristics

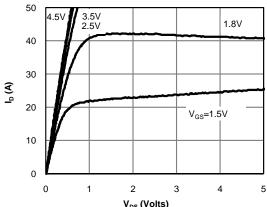
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			20	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =2A , T _J =25℃			1.2	V

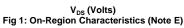
Note

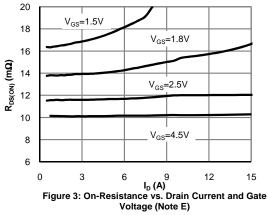
- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.1mH, I_{AS} =20A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

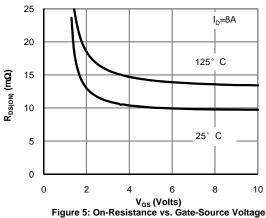


Typical Characteristics

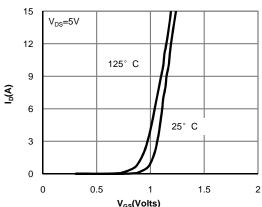








(Note E)



V_{GS}(Volts)
Figure 2: Transfer Characteristics (Note E)

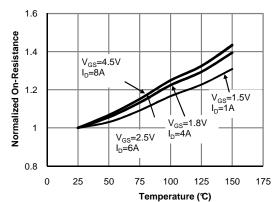
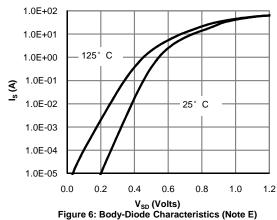
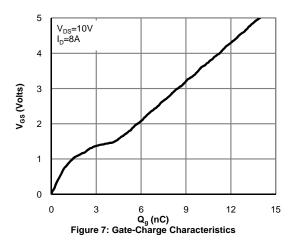


Figure 4: On-Resistance vs. Junction gemperature
(Note E)







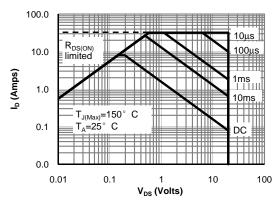
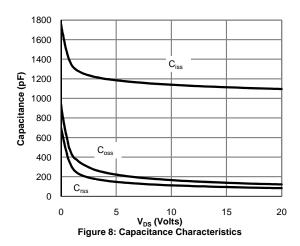
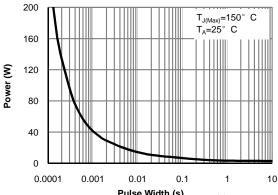
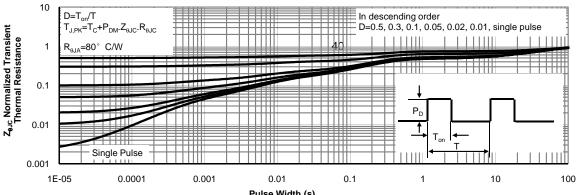


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)





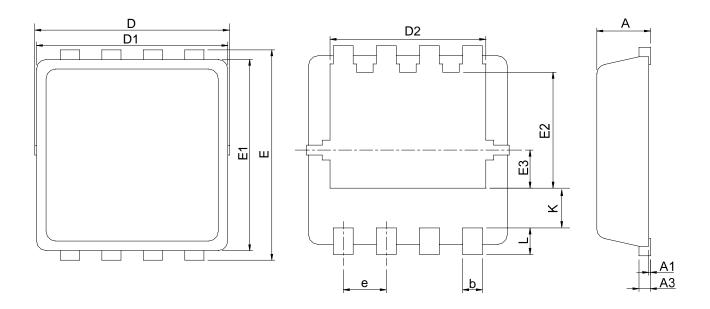
Pulse Width (s)
Figure 10: Single Pulse Power Rating Junction-toAmbient (Note F)



Pulse Width (s)
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

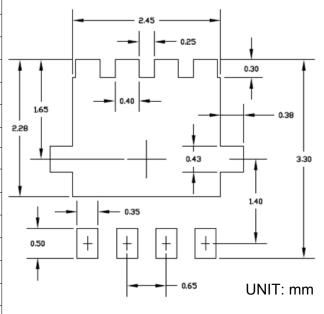


DFN3x3A-8_EP1



Ş	DFN3x3A-8_EP1_P				
SYMBOL	MILLIM	MILLIMETERS		HES	
Ď	MIN.	MAX.	MIN.	MAX.	
Α	0.80	1.00	0.031	0.039	
A1	0.00	0.05	0.000	0.002	
А3	0.10	0.25	0.004	0.010	
b	0.24	0.35	0.009	0.014	
D	2.90	3.30	0.114	0.130	
D1	2.90	3.10	0.114	0.122	
D2	2.25	2.45	0.089	0.096	
Е	3.10	3.30	0.122	0.130	
E1	2.90	3.10	0.114	0.122	
E2	1.65	1.85	0.065	0.073	
E3	0.56	0.58	0.022	0.023	
е	0.65 BSC		0.02	6 BSC	
K	0.475	0.775	0.019	0.031	
L	0.30	0.50	0.012	0.020	

RECOMMENDED LAND PATTERN





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